

Bill of Materials

TI DESIGNS TIDA00594

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	C1	0.47uF	CAP, CERM, 0.47 µF, 16 V, +/- 10%, X5R, 0402	MuRata	GRM155R61C474KE01		0402	
2	5	C2, C3, C4, C6, C7	0.1uF	CAP, CERM, 0.1 μF, 10 V, +/- 10%, X5R, 0402	MuRata	GRM155R61A104KA01D		0402	
3	1	C5	1uF	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402	TDK	C1005X5R1C105K050B C		0402	
4	2	D1, D2	5.1V	Diode, Zener, 5.1 V, 300 mW, SOT-23	Diodes Inc.	AZ23C5V1-7-F		SOT-23	
5	3	J1, J3, J4		Header, 100mil, 2x1, Tin, TH	Sullins Connector Solu	PEC02SAAN		Header, 2 PIN, 100mil, Tin	
6	2	J2, J5		Header (friction lock), 100mil, 4x1, R/A, TH	Molex	22-05-3041		4x1 R/A Header	
7	1	J6		Header, 100mil, 3x1, Tin, TH	Sullins Connector Solu	PEC03SAAN		Header, 3 PIN, 100mil, Tin	
8	1	R1	4.7k	RES, 4.7 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04024K70JNED		0402	
9	8	R2, R3, R6, R7, R8, R9, R10, R11	100	RES, 100, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402100RJNED		0402	
10	2	R4, R5	10k	RES, 10 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040210K0JNED		0402	
11	1	R12	0.01	RES, 0.01, 1%, 0.25 W, 0805	Vishay-Dale	WSL0805R0100FEA18		0805	
12	1	RT1	10.0k ohm	Thermistor NTC, 10.0k ohm, 1%, Disc, 5x8.4 mm	SEMITEC Corporation	103AT-2		Disc, 5x8.4 mm	
13	2	TB1, TB2		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS		7.0x8.2x6.5mm	
14	8	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8	SMT	Test Point, Miniature, SMT	Keystone	5015		Testpoint_Keyst one_Miniature	
15	1	U1		Single Cell Li-lon Battery Fuel Gauge for Battery Pack Integration, YZF0015BBBP	Texas Instruments	BQ27546YZFR-G1	BQ27546YZFT-G1	YZF0015BBBP	

Notes:

Unless otherwise noted in the Alternate Part column, all parts may be substituted with equivalents.

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